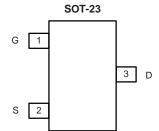
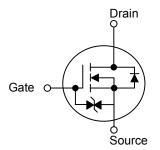


# N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (mA)		
60	2 at V <sub>GS</sub> = 10 V	300		







#### **FEATURES**

- Low On-Resistance: 2  $\Omega$
- Low Threshold: 2 V (typ.)
- Low Input Capacitance: 25 pF
- Fast Switching Speed: 25 ns
- Low Input and Output Leakage
- DT-Trench Power MOSFET
- 1200V ESD Protection
- Compliant to RoHS Directive 2002/95/EC

#### BENEFITS

- Low Offset Voltage
- Low-Voltage Operation
- Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

#### **APPLICATIONS**

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V <sub>DS</sub>	60	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20				
	T <sub>A</sub> = 25 °C	L	300	mA		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>b</sup>	T <sub>A</sub> = 100 °C	Ι <sub>D</sub>	190			
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	800			
	T <sub>A</sub> = 25 °C	D	0.35	W		
Power Dissipation <sup>b</sup>	T <sub>A</sub> = 100 °C	PD	0.14			
Maximum Junction-to-Ambient <sup>b</sup>		R <sub>thJA</sub>	350	°C/W		
Operating Junction and Storage Temperature Range		T <sub>J,</sub> T <sub>stg</sub>	- 55 to 150	°C		

Notes:

a. Pulse width limited by maximum junction temperature.

b. Surface Mounted on FR4 board.

\* Pb containing terminations are not RoHS compliant, exemptions may apply.

ROHS\*

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<b>SPECIFICATIONS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted							
			Limits				
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V$ , $I_{D} = 10 \mu A$	60			v	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	1		2.5	v	
		$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 10	μA	
		$V_{DS} = 0 V, V_{GS} = \pm 15 V$			1		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 10 V$			± 150	nA	
		$V_{DS} = 0 V, V_{GS} = \pm 10 V, T_{J} = 85 °C$			± 1000		
		$V_{DS} = 0 V, V_{GS} = \pm 5 V$			± 100		
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS}$ = 60 V, $V_{GS}$ = 0 V , $T_{J}$ = 125 °C			500		
2		$V_{GS}$ = 10 V, $V_{DS}$ = 7.5 V	800			mA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$	500				
	6	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 500 mA			2		
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS}$ = 4.5 V, I <sub>D</sub> = 200 mA			4	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 200 mA	100			mS	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 200 mA, V <sub>GS</sub> = 0 V			1.3	V	
Dynamic <sup>a</sup>			•	•			
Total Gate Charge	Qg	$V_{DS}$ = 10 V, $V_{GS}$ = 4.5 V $I_D \cong 250 \text{ mA}$		0.4	0.6	nC	
Input Capacitance	C <sub>iss</sub>			30		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V f = 1 MHz		6			
Reverse Transfer Capacitance	C <sub>rss</sub>			2.5			
Switching <sup>a, b, c</sup>							
Turn-On Time	t <sub>d(on)</sub>	$V_{DD}$ = 30 V, $R_{L}$ = 150 $\Omega$			25		
Turn-Off Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong~$ 200 mA, $\text{V}_\text{GEN}$ = 10 V, R_G = 10 $\Omega$			35	ns	

Notes:

a. For DESIGN AID ONLY, not subject to production testing.

b. Pulse test: PW  $\leq$  300 µs duty cycle  $\leq$  2 %.

c. Switching time is essentially independent of operating temperature.

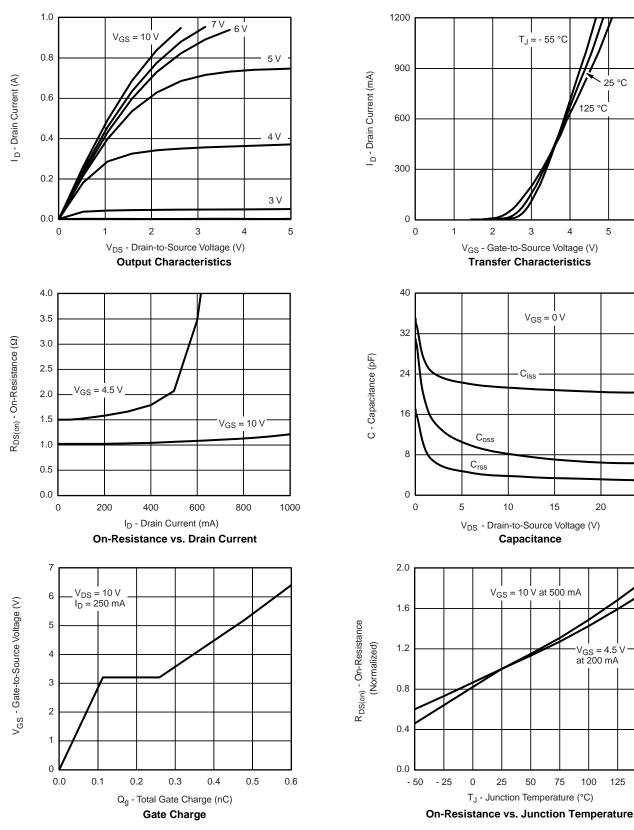
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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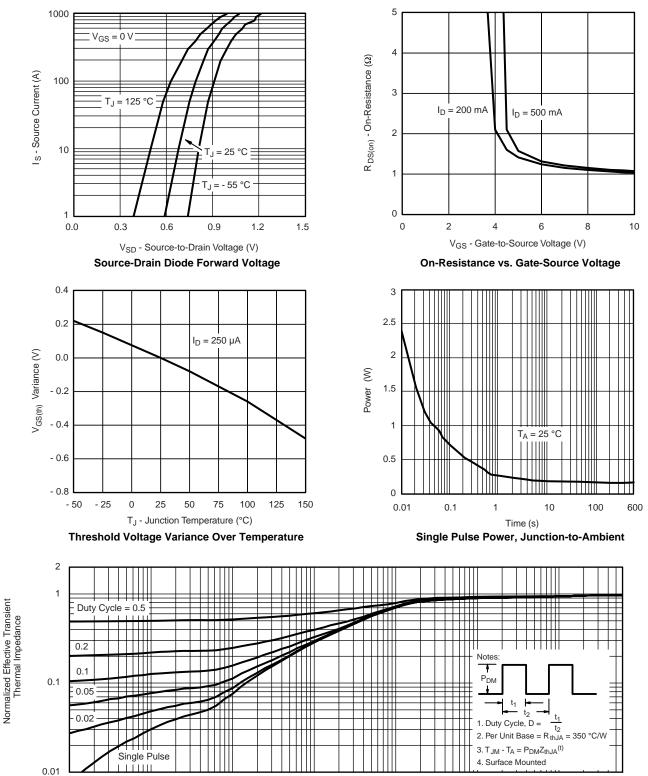




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1

10

100

600

10-1

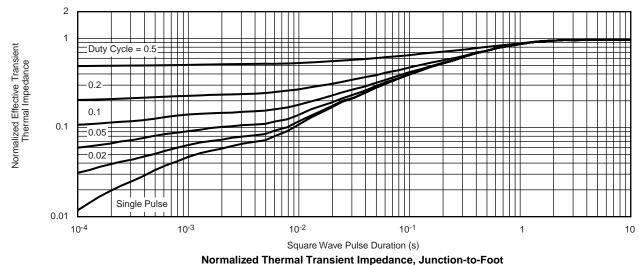
10<sup>-3</sup>

10-2

10-4



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### **THERMAL RATINGS** ( $T_A$ = 25 °C, unless otherwise noted)

#### Note

The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

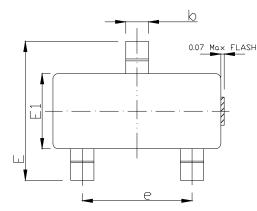
- Normalized Transient Thermal Impedance Junction-to-Foot (25 C)

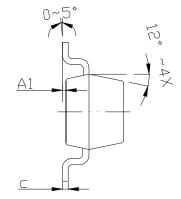
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

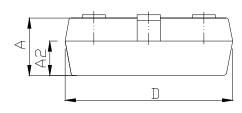


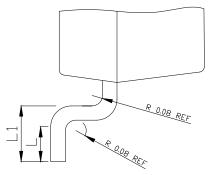
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## SOT-23 PACKAGE OUTLINE









### COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MILLIMETER			
	MIN	NOM	MAX	
А	0.80	1.00	1.30	
A1	0.00	0.05	0.15	
b	0.25	0.40	0.55	
с	0.11 BSC			
D	2 <b>. 6</b> 0	2.90	3 <b>. 2</b> 0	
Е	2.10	2.40	2.70	
E1	1.10	1.30	1.48	
е	1.90 BSC			
L	0.17	—	_	
L1	0.28	0.40	0.53	
A2	0.60 REF			



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